

数字集成电路设计 Digital Integrated Circuit Design

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上海交通大学电子信息与电气工程学院



What we talk about?

- How to qualify?
- What is the value of the course?
- IC history
- Why Integrated Circuit is the soul of IT?
- Why COST?
- China IC history

Lab assistant

- teacher: Yuzhuo FU/Yanan SUN
 - Email:yzfu@sjtu.edu.cn
 - Office Room: 205 room Weidianzi Blgs
 - Office hours:1h/week
- Lab assistant: XXX Master Candidate
 - Email:XXX
 - weidianzi blgs 205 cofferoom
 - Office hours:?

Course Instruction

- Course named: Digital Integrated
 Circuit
- Course code: SOME-021
- Course type: fundamental
- credit: 64 hours/4 credits
- Pre:digital logic, circuit basic

Teacher

Dr. Yuzhuo FU, Professor

- Phone: 13671916822
- Email: yzfu@sjtu.edu.cn
- Office Room: Rm 417/205, Building of Microelectronics
- Office hours: Thursday(all day), Friday(morning)

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- Office Room: Rm 418, Building of Microelectronics

CAT-Intelligent Computer Architecture and Technology



- 团队组成
 - 教授1人,讲师2人
 - 研究生15人左右(博士在读7人)
- 主要研究方向
 - 深度学习/机器学习应用及加速设计
 - 复杂系统故障量化分析及加固技术
- 合作单位
 - Intel、Google、阿里云、航天八院、上汽集团、中通客车等

SJTU-icat.github.io

参课教师介绍

孙亚男



副教授,博士 上海交通大学

- 2019/01-至今,上海交通大学微纳 电子学系,副教授
- 2015/10-2018/12,上海交通大学 微纳电子学系,讲师
- 2009/09-2015/06,香港科技大学电子与计算机工程学系,博士
- 2005/09-2009/07,上海交通大学 微电子学院,学士

科研方向

- 基于新型纳米技术的高能效 及高良率集成电路设计
- 存内计算电路及三维集成 电路设计
- 神经网络加速器及边缘计算

成果简介

在IEEE JSSC、TCAS-I、IEEE TCAS-II、IEEE TCAS-II、IEEE TVLSI、IEEE TED、IEEE TCAD等集成电路 领域高水平期刊和IEEE ISSCC、DAC、DATE、ISCAS等重要国际会议发表40余篇学术论文

科研项目

主持国家自然科学面上基金、青年自然科学基金、上海市扬帆计划等 多项;参与国家重点研发计划等多项。

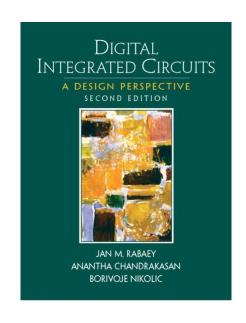
荣誉奖项

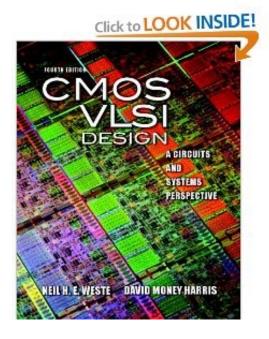
- IEEE欧洲设计自动化与测试会议(DATE)最佳论文提名奖(2020)
- "华为杯"第三届中国研究生创"芯"大赛,优秀指导教师奖(2020)
- 全国大学生集成电路创新创业大赛, 优秀指导教师奖(2019)
- ■上海市"青年科技英才扬帆计划"(2017)
- 北京大学生集成电路设计大赛暨全国邀请赛, 优秀指导教师奖(2016)
- IEEE微电子国际会议(ICM)最佳论文奖(2014)

Textbook

- Digital integrated circuit Jan M.Rabaey
- CMOS VLSI design- a circuits and systems perspective
 Meil H.E.Weste, addison wesley press

《CMOS超大规模集成电路设计》





Method of course

- Time, location
 - 1-16 weeks
 - Mon. 3-4[10:00-11:40], Room 东下302
 - Wed. 1-2[08:00-09:40], Room 东下302
- Materials
 - Please pre-read the slides before the lessons
- Quiz
 - Finish at the end of each lesson
- Homework
 - Close by the end of the week
- Review 10%, New Contents 90%

Qualification

授课方式 (课时)			作业 (份)	实 (课		考 (%	试 欠)	
课堂 教学	实验	讲 座	习题课	作业	课内	课 外	测验	考试
50	2	4	4	30	0	6	30	2

	实验	考试			
作业	报告	测验	期中考试	期末 考试	
0.6 ₃₀	44	0.4 ₃₀	27	27	



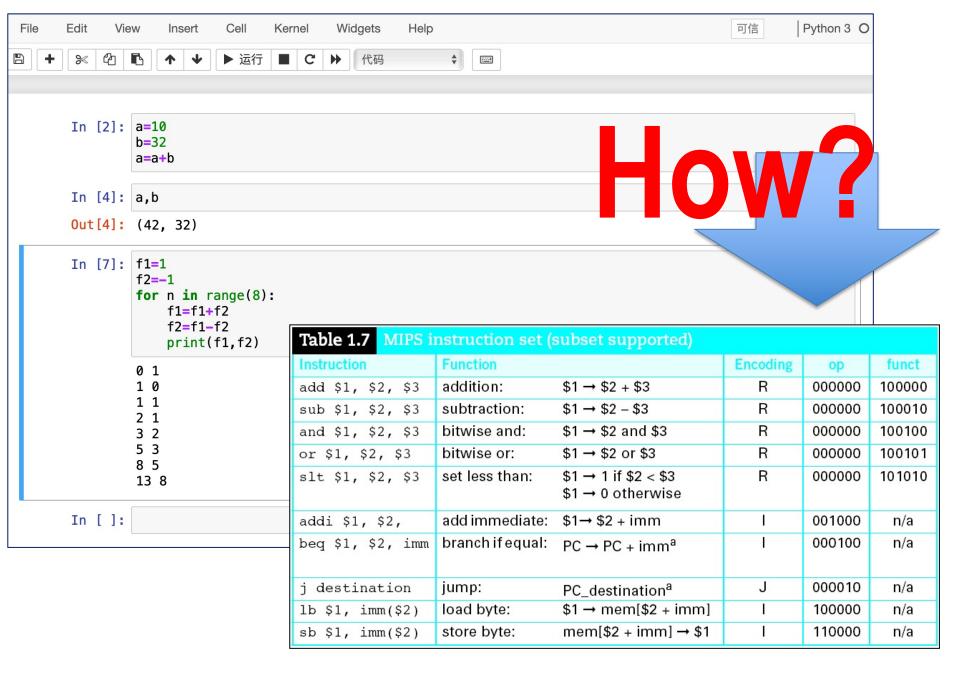
Some references

- http://www.itrs.net/
- http://www.lib.sjtu.edu.cn
 IEEE conferences and journals
- IEEE Journal of Solid-State Circuits (JSSC)
- IEEE International Solid-State Circuits Conference(ISSCC)
- Symposium on VLSI Circuits (VLSI)

Classroom Regulations

- No Breakfast
- No Chat

Who is DIC?

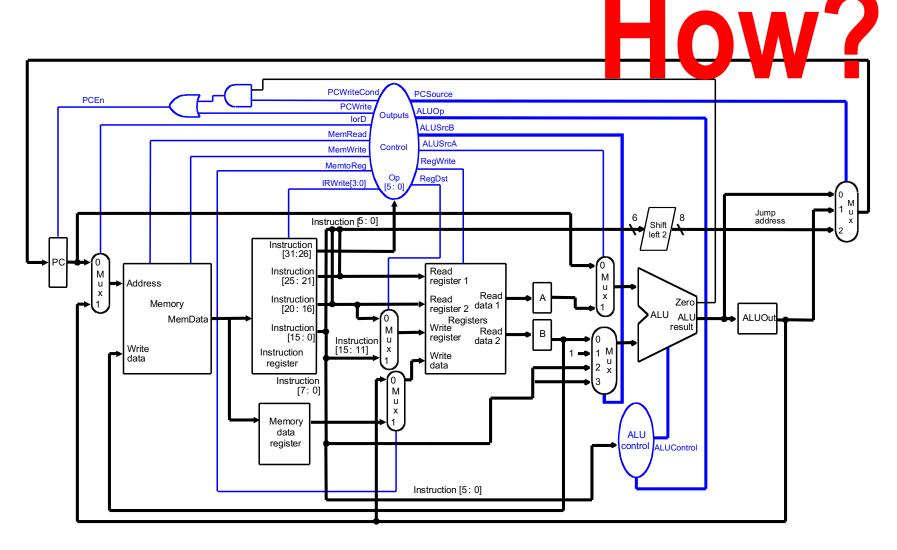


```
# fib.asm
# Register usage: $3: n $4: f1 $5: f2
# return value written to address 255
fib: addi $3, $0, 8  # initialize n=8
    addi $4, $0, 1  # initialize f1 = 1
    addi $5, $0, -1  # initialize f2 = -1

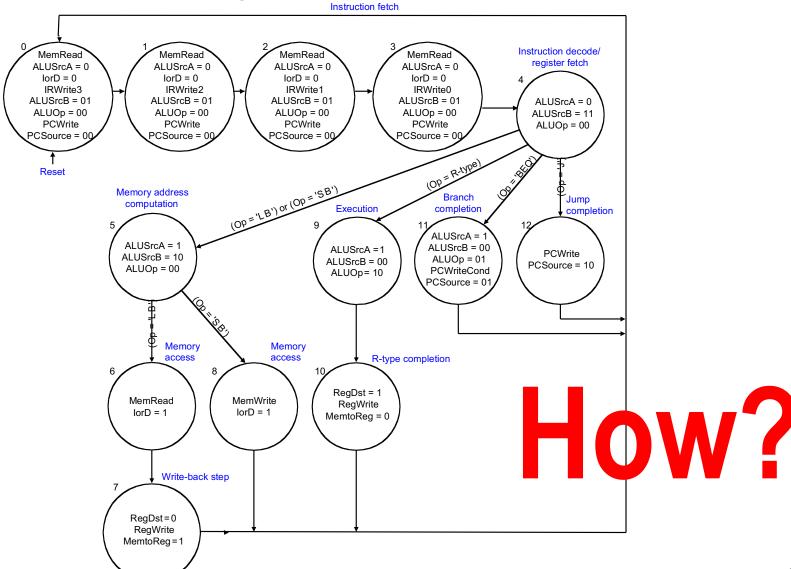
loop: beq $3, $0, end  # Done with loop if n = 0
    add $4, $4, $5  # f1 = f1 + f2
    sub $5, $4, $5  # f2 = f1 - f2
    addi $3, $3, -1  # n = n - 1
    j loop  # repeat until done
end: sb $4, 255($0)  # store result in address 255
```

			Hexadecimal
Instruction	Binary	Encoding	Encoding
addi \$3, \$0, 8	001000	00000 00011 000000000001000	20030008
addi \$4, \$0, 1	001000	00000 00100 000000000000001	20040001
addi \$5, \$0, -1	001000	00000 00101 111111111111111	2005ffff
beq \$3, \$0, end	000100	00011 00000 000000000000101	10600005
add \$4, \$4, \$5	000000	00100 00101 00100 00000 100000	00852020
sub \$5, \$4, \$5	000000	00100 00101 00101 00000 100010	00852822
addi \$3, \$3, -1	001000	00011 00011 111111111111111	2063ffff
j loop	0000	000000000000000000000000000000000000000	08000003
sb \$4, 255(\$0)	110000	00000 00100 000000011111111	a00400ff

MIPS Microarchitecture



Multicycle Controller



Gate-level Netlist

```
module carry(input a, b, c,
             output cout)
   wire x, y, z;
                              g2
                           a
    and g1(x, a, b);
    and g2(y, a, c);
    and q3(z, b, c);
    or q4(cout, x, y, z);
endmodule
```

l have learned

18/35

Transistor-Level Netlist

```
module carry(input a, b, c,
            output cout)
                                CMOS?pseudo nMOS?
     wire i1, i2, i3, i4, cn; Pass logic? Dynamic logic?
     tranif1 n1(i1, 0, a);
     tranif1 n2(i1, 0, b);
     tranif1 n3(cn, i1, c);
     tranif1 n4(i2, 0, b);
                                                         cout
     tranif1 n5(cn, i2, a);
     tranif0 p1(i3, 1, a);
                              a—[n1 b—[n2
     tranif0 p2(i3, 1, b);
     tranif0 p3(cn, i3, c);
     tranif0 p4(i4, 1, b);
     tranif0 p5(cn, i4, a);
                                   Speed? Power? Area?
     tranif1 n6(cout, 0, cn);
     tranifo p6(cout, 1, cn);
```

endmodule

DIC is coming

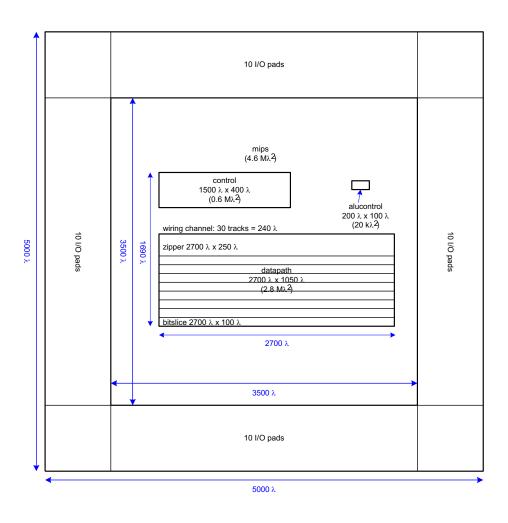
SPICE Netlist

```
.SUBCKT CARRY A B C COUT VDD GND
MN1 I1 A GND GND NMOS W=1U L=0.18U AD=0.3P AS=0.5P
MN2 T1 B GND GND NMOS W=1U T=0.18U AD=0.3P AS=0.5P
MN3 CN C T1 GND NMOS W=1U T,=0.18U AD=0.5P AS=0.5P
MN4 I2 B GND GND NMOS W=1U L=0.18U AD=0.15P AS=0.5P
MN5 CN A T2 GND NMOS W=1U _{1}=0.18U AD=0.5P AS=0.15P
MP1 I3 A VDD VDD PMOS W=2U L=0.18U AD=0.6P AS=1 P
MP2 T3 B VDD VDD PMOS W=2U I=0.18U AD=0.6P AS=1P
MP3 CN C T3 VDD PMOS W=2U T=0.18U AD=1P AS=1P
MP4 I4 B VDD VDD PMOS W=2U L=0.18U AD=0.3P AS=1P
MP5 CN A T4 VDD PMOS W=2U T=0.18U AD=1P AS=0.3P
MN6 COUT CN GND GND NMOS W=2U L=0.18U AD=1P AS=1P
MP6 COUT CN VDD VDD PMOS W=4U I=0.18U AD=2P AS=2P
CI1 II GND 2FF
CI3 I3 GND 3FF
CA A GND 4FF
CB B GND 4FF
CC C GND 2FF
CCN CN GND 4FF
CCOUT COUT GND 2FF
.ENDS
```

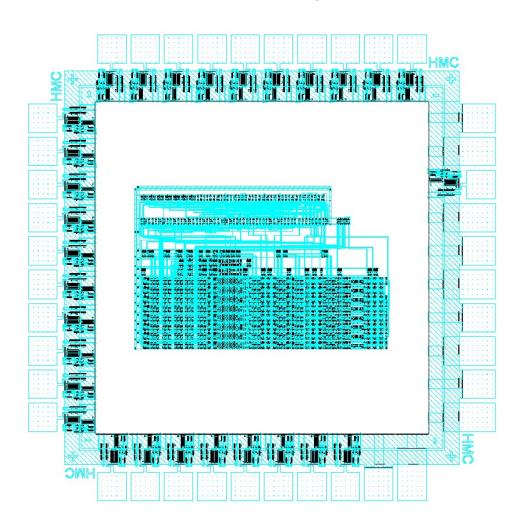
Physical Design

- Floorplan
- Standard cells
 - Place & route
- Datapaths
 - Slice planning
- Area estimation

MIPS Floorplan

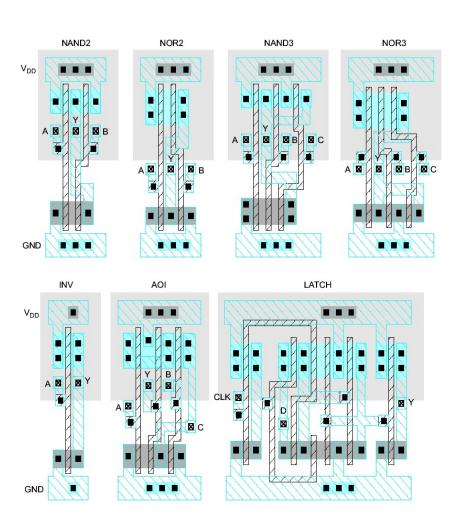


MIPS Layout



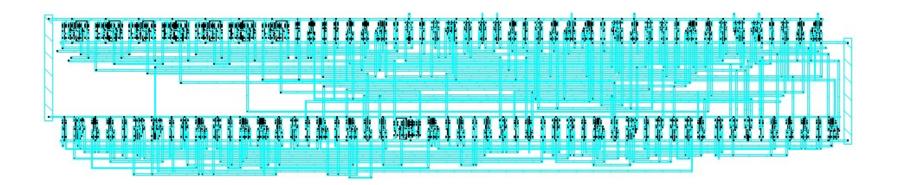
Standard Cells

- Uniform cell height
- Uniform well height
- M1 V_{DD} and GND rails
- M2 Access to I/Os
- Well / substrate taps
- Exploits regularity



Synthesized Controller

- Synthesize HDL into gate-level netlist
- Place & Route using standard cell library



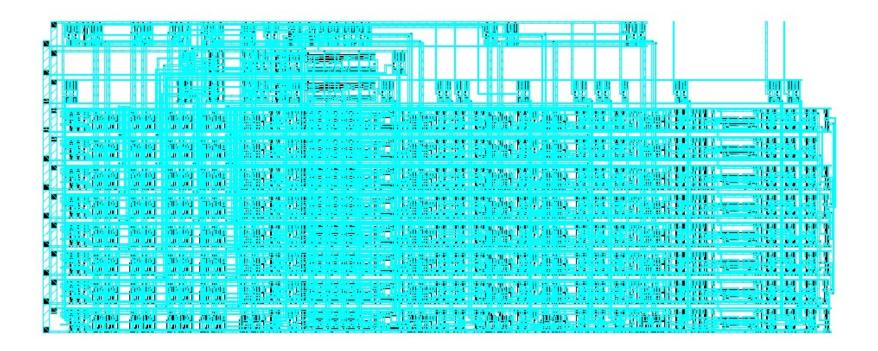
Pitch Matching

- Synthesized controller area is mostly wires
 - Design is smaller if wires run through/over cells
 - Smaller = faster, lower power as well!
- Design snap-together cells for datapaths and arrays
 - Plan wires into cells
 - Connect by abutment
 - Exploits locality
 - Takes lots of effort

Α	Α	Α	Α	В
Α	Α	Α	Α	В
Α	Α	Α	Α	В
Α	Α	Α	Α	В
С		С		D

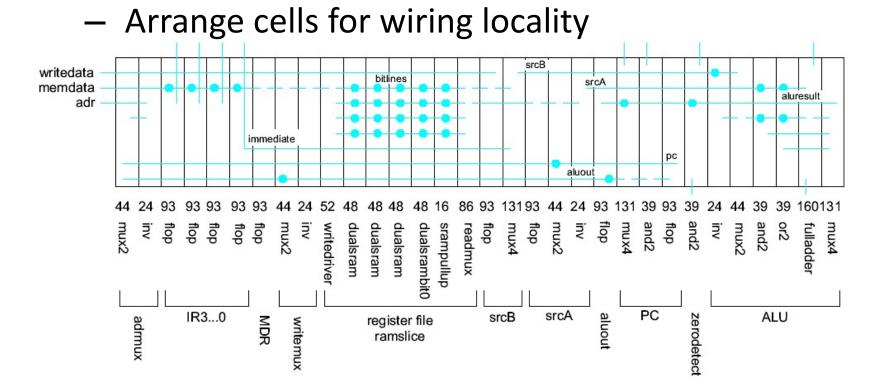
MIPS Datapath

- 8-bit datapath built from 8 bitslices (regularity)
- Zipper at top drives control signals to datapath



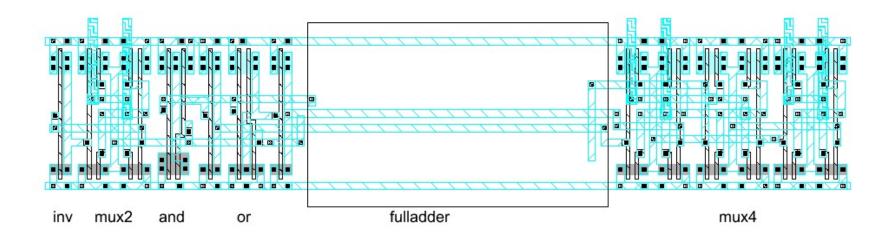
Slice Plans

- Slice plan for bitslice
 - Cell ordering, dimensions, wiring tracks



MIPS ALU

Arithmetic / Logic Unit is part of bitslice



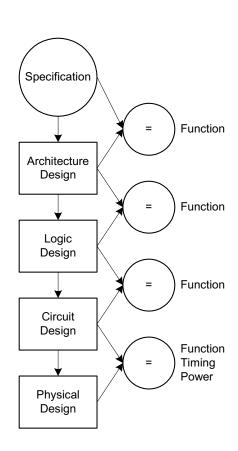
Area Estimation

- Need area estimates to make floorplan
 - Compare to another block you already designed
 - Or estimate from transistor counts
 - Budget room for large wiring tracks
 - Your mileage may vary!

Table 1.10 Typical layout densities				
Element	Area			
random logic (2-level metal process)	$1000 - 1500 \lambda^2$ / transistor			
datapath	$250 - 750 \lambda^2$ / transistor			
	or 6 WL + 360 λ^2 / transistor			
SRAM	1000 λ² / bit			
DRAM (in a DRAM process)	$100 \lambda^2 / \text{bit}$			
ROM	$100 \lambda^2 / \text{bit}$			

Design Verification

- Fabrication is slow & expensive
 - MOSIS: \$??K, 3 months
 - State of art: \$??M, 1 month
- Debugging chips is very hard
 - Limited visibility into operation
- Prove design is right before building!
 - Logic simulation
 - Ckt. simulation / formal verification
 - Layout vs. schematic comparison
 - Design & electrical rule checks
- Verification is > 50% of effort on most chips!



Fabrication & Packaging

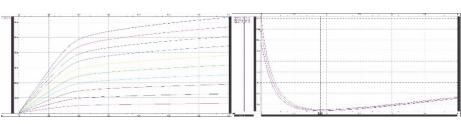
- Tapeout final layout
- Fabrication
 - 6, 8, 12" wafers
 - Optimized for throughput, not latency (10 weeks!)
 - Cut into individual dice
- Packaging
 - Bond gold wires from die I/O pads to package

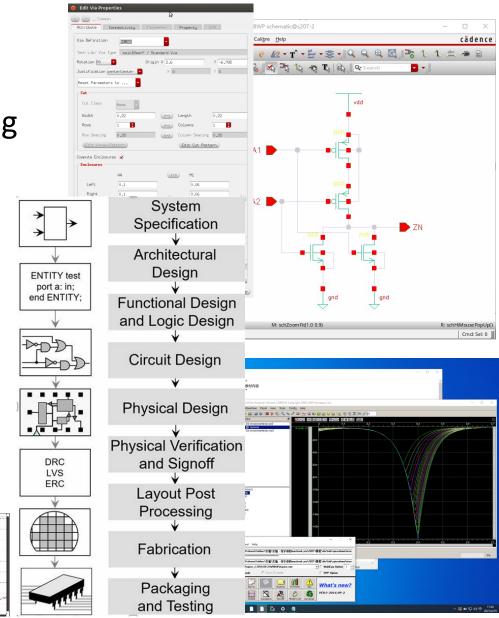
Testing

- Test that chip operates
 - Design errors
 - Manufacturing errors
- A single dust particle or wafer defect kills a die
 - Yields from 90% to < 10%
 - Depends on die size, maturity of process
 - Test each part before shipping to customer

DIC Target

- ✓ Transistor level Optimizing
 - Inverter
 - Combinational logic
 - Sequential logic
 - Datapath design
- ✓ Modeling
 - Clocking issues
 - Wire issues
- ✓ Tooling
 - HSPICE programming
 - Cadence flow





Why digital circuits?

- Design and implement the module libraries
- Critical timing path still need circuit design
- Some technologies tend to be pushed to its limit need circuit design
- New design issues and constraints tend to emerge over time
- Model not always show the truth

We are the pioneers of the NEW IC technology!